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## P1086

### **P-Channel Switch**

- This device is designed for low level analog switching sample and hold circuits and chopper stabilized amplifiers.
- Sourced from process 88.



# Absolute Maximum Ratings T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
$V_{DG}$	Drain-Gate Voltage	- 30	V
$V_{GS}$	Gate-Source Voltage	30	V
I <sub>GF</sub>	Forward Gate Current	50	mA
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 ~ +150	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150 degrees C.
   These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

## Electrical Characteristics T<sub>C</sub>=25°C unless otherwise noted

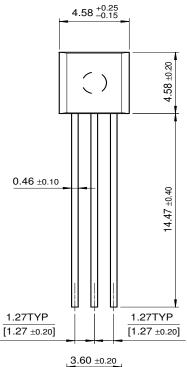
Symbol	Parameter	Test Condition		Min.	Тур.	Max.	Units
BV <sub>GSS</sub>	Gate-Source Breakdown Voltage	$V_{DS} = 0V$ , $IG = 1\mu A$		30			V
I <sub>GSS</sub>	Gate Reverse Current	V <sub>GS</sub> = 15V				2	nA
I <sub>D</sub> (off)	Drain Cutoff Leakage Current	V <sub>DS</sub> = 15V				10	nA
		$V_{GS} = 12V$	T = +85°C			0.5	μΑ
I <sub>DGO</sub>	Drain-Gate Leakage Current	V <sub>DG</sub> = 15V				2	NΑ
		I <sub>S</sub> = 0	T = +85°C			0.1	μΑ
I <sub>DSS</sub>	Zero-Gate Voltage Drain Current	V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V		10			mA
V <sub>GS</sub> (off)	Gate-Source Cutoff Voltage	$V_{DS} = 15V, I_D = 1\mu A$				10	V
V <sub>DS</sub> (on)	Drain-Source On Voltage	$V_{GS} = 0V$ , $I_D = 6mA$				0.5	V
r <sub>DS</sub> (on)	Drain-Source On Resistance	$V_{GS} = 0V$ , $I_D = 1mA$				75	Ω
r <sub>ds</sub> (on)	Drain-Source On Resistance	$V_{GS} = 0V, I_D = 0, f = 1kHz$				75	Ω
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1MHz				45	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 12V, f = 1MHz				10	pF
t <sub>d</sub> (on)	Trun On Time	$V_{DD} = -6V$ $V_{GS}(off) = +12V$ $R_L = 910\Omega$ $I_D(on) = 6mA$				15	ns
t <sub>r</sub>	Rise Time					20	ns
t <sub>d</sub> (off)	Trun Off Time					15	ns
t <sub>f</sub>	Fall Time					50	ns

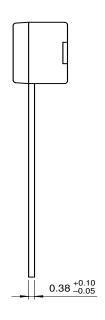
# Thermal Characteristics $T_A=25$ °C unless otherwise noted

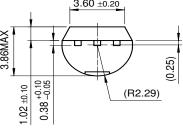
Symbol	Parameter	Max.	Units
P <sub>D</sub>	Total Device Dissipation	350	mW
	Derate above 25°C	2.8	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W

# **Package Dimensions**

TO-92







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EnSigna™	I <sup>2</sup> C <sup>TM</sup>	OCXTM	RapidConfigure™	UHC™
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Datasheet Identification	Product Status	Definition
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